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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
10/758,188	01/15/2004	In Su Kim	20063/OG03-046	5382
34431	7590 12/21/2005		EXAMINER	
HANLEY, I	FLIGHT & ZIMMER	SMITH, BRADLEY		
SUITE 4220	EK DRIVE		ART UNIT	PAPER NUMBER
CHICAGO, IL 60606			2891	

DATE MAILED: 12/21/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)	N
		10/758,188	KIM, IN SU	
	Office Action Summary	Examiner	Art Unit	
		Bradley K. Smith	2891	
Period f	The MAILING DATE of this communication app or Reply	ears on the cover sheet with the	correspondence addre	9ss
A SH WHIC - Exte after - If NC - Failt Any	HORTENED STATUTORY PERIOD FOR REPLY CHEVER IS LONGER, FROM THE MAILING DATE of time may be available under the provisions of 37 CFR 1.13 SIX (6) MONTHS from the mailing date of this communication. Depriod for reply is specified above, the maximum statutory period we ure to reply within the set or extended period for reply will, by statute, reply received by the Office later than three months after the mailing led patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION  36(a). In no event, however, may a reply be will apply and will expire SIX (6) MONTHS from the application to become ABANDON	ON. timely filed om the mailing date of this comm	
Status				
	Responsive to communication(s) filed on 10/s/s This action is <b>FINAL</b> . 2b) This Since this application is in condition for allowar closed in accordance with the practice under E	action is non-final. nce except for formal matters, p		nerits is
Disposit	ion of Claims		. •	
5)□ 6)⊠ 7)⊠		vn from consideration.		
Applicat	ion Papers		. •	
10)⊠	The specification is objected to by the Examine The drawing(s) filed on <u>05 October 2005</u> is/are: Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct The oath or declaration is objected to by the Ex	a) $\boxtimes$ accepted or b) $\square$ objected drawing(s) be held in abeyance. So ion is required if the drawing(s) is consistent $\square$	see 37 CFR 1.85(a). Objected to. See 37 CFR	1.121(d).
Priority :	under 35 U.S.C. § 119		. •	
12) <mark>X</mark> (a)	Acknowledgment is made of a claim for foreign  All b) Some * c) None of:  1. Certified copies of the priority documents  2. Certified copies of the priority documents  3. Copies of the certified copies of the priority application from the International Bureau  See the attached detailed Office action for a list	s have been received. s have been received in Applica ity documents have been recei ı (PCT Rule 17.2(a)).	ation No ved in this National Sta	age
Attachmen  1) Notice 2) Notice	et(s) ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-948)	4)		
3) 🔲 Infor	ce of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) or No(s)/Mail Date		Patent Application (PTO-15	52)

## **DETAILED ACTION**

# Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 1. Claims 1, 3-5 are rejected under 35 U.S.C. 103(a) as being unpatentable over Dong et al. (KR2003094442) in view of Okumura et al. Dong et al. disclose depositing an oxide layer, a first conducting layer for a floating gate, a dielectric layer, and a second conducting layer for a control gate in sequence on a semiconductor substrate including a device isolation layer; forming gates by removing some part of the oxide layer, the first conducting layer, the dielectric layer, and the second conducting layer; forming a mask pattern for a self-aligned source over the substrate including the gates'. removing the device isolation layer exposed between the gates; performing an ion implantation process', and eliminating damage generated during the ion implantation process or the removal process of the device isolation layer ( see detailed description). With regards to claim 3 Dong et al. disclose the first and second conductive layers are formed of polysilicon. With regards to claim 4, Dong et al. disclose and ONO structure (212, 213, 214). With respect to claim 5, Dong et al. inherently disclose the use of dry etching. However Dong et al. fails to disclose washing the substrate and forming an insulation layer, whereas Okumura et al. disclose washing the substrate and forming an insulation layer. Therefore it would have been obvious to one of ordinary skill in the art

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at the time the invention was made to combine the teachings of Dong et al. and

Okumura et al. because washing the substrate would remove any defects that would interfere in the formation of the insulation layer.

2. Claim1, 3-5 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yang et al. (US Patent 6,784,061) in view of Okumura et al. Yang disclose depositing an oxide layer, a first conducting layer for a floating gate, a dielectric layer, and a second conducting layer for a control gate in sequence on a semiconductor substrate including a device isolation layer; forming gates by removing some part of the oxide layer, the first conducting layer, the dielectric layer, and the second conducting layer; forming a mask pattern for a self-aligned source over the substrate including the gates', removing the device isolation layer exposed between the gates; performing an ion implantation process', and eliminating damage generated during the ion implantation process or the removal process of the device isolation layer (eliminating the damage would be inherent since the ion implant has to be annealed in order to activate the ions) (see figure 6 and column 3 lines 5-25). With regards to claim 3 Yang et al. disclose the first and second conductive layers are formed of polysilicon (column 1 lines 60-65). With regards to claim 4, Yang et al. disclose and ONO structure (column 1 lines 60-65). With respect to claim 5, Yang et al. disclose the use of dry etching (column 3 lines 5-25). However Yang et al. fails to disclose washing the substrate and forming an insulation layer, whereas Okumura et al. disclose washing the substrate and forming an insulation layer. Therefore it would have been obvious to one of ordinary skill in the art at the time the invention was made to combine the teachings of Yang et al. and Okumura et al.

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because washing the substrate would remove any defects that would interfere in the formation of the insulation layer.

Claim 6 is rejected under 35 U.S.C. 103(a) as being unpatentable over Yang et al. (US Patent 6,784,061) in view of Okumura et al. Yang et al. and Okumura disclose the claimed invention except for applying a top power between 800W and 1500W under a pressure between 100 mTorr and 300 mTorr. It would have been obvious to one of ordinary skill in the art at the time the invention was made to applying a top power between 800W and 1500W under a pressure between 100 mTorr and 300 mTorr, since it has been held that where the general conditions of a claim are disclosed in the prior art, discovering the optimum or working ranges involves only routine skill in the art. In re Aller, 105 USPQ 233. Furthermore the particular power and pressure are well within normal parameters.

## Allowable Subject Matter

- 3. Claims 7-12 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.
- 4. The following is a statement of reasons for the indication of allowable subject matter: the prior art of record neither teaches nor suggests within the context of the entire claim, dry etch using C4F8, CHF3, O2 and Ar at particular pressures (claim 7), the damage is removed by a chemical dry etch process (claims 8-12).

#### Allowable Subject Matter

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The indicated allowability of claim 2 is withdrawn in view of the newly discovered reference(s) to Okumura.

#### Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Bradley K. Smith whose telephone number is 571-272-1884. The examiner can normally be reached on 10-6.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Bill Baumeister can be reached on 571-272-1722. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Bradley K Smith Primary Examiner Art Unit 2891